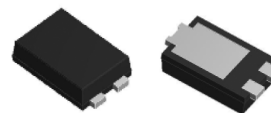
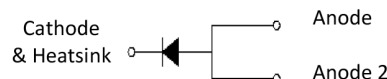


## Features

- Schottky barrier diodes
- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Solder dip 260 °C, 10 s
- Low profile - typical height of 1.1 mm
- Heatsink design
- High temperature soldering guaranteed: 260°C/10 seconds
- Halogen-free according to IEC 61249-2-21 definition



eSGC (TO-277)



## Typical Applications

For low voltage high frequency inverters, DC/DC converters and polarity protection application.

## Maximum Ratings (TA = 25 °C unless otherwise noted)

| Parameter                                                                          | Symbol               | SGC1020S    | SGC1030S | SGC1040S | SGC1045S | Unit |
|------------------------------------------------------------------------------------|----------------------|-------------|----------|----------|----------|------|
| Maximum repetitive peak reverse                                                    | VRRM                 | 20          | 30       | 40       | 45       | V    |
| Maximum RMS voltage                                                                | VRMS                 | 14          | 21       | 28       | 31.5     | V    |
| Maximum DC blocking voltage                                                        | VDC                  | 20          | 30       | 40       | 45       | V    |
| Maximum average forward rectified current                                          | IF(AV) <sup>1)</sup> | 10.0        |          |          |          | A    |
|                                                                                    | IF(AV) <sup>2)</sup> | 5.0         |          |          |          |      |
| Peak forward surge current 8.3 ms single half sine-wave superimposed on rated load | IFSM                 | 280         |          |          |          | A    |
| Operating junction and storage temperature range                                   | TJ, TSTG             | -55 to +150 |          |          |          | °C   |

## Electrical Characteristics (TA = 25 °C unless otherwise noted)

| Parameter                                | Test Conditions     |                       | Symbol           | TYP. | MAX. | Unit  |
|------------------------------------------|---------------------|-----------------------|------------------|------|------|-------|
| Instantaneous forward voltage            | I <sub>F</sub> =1A  | T <sub>A</sub> =25°C  | V <sub>F</sub>   | 0.30 | 0.35 | Volts |
|                                          | I <sub>F</sub> =2A  |                       |                  | 0.33 | 0.38 |       |
|                                          | I <sub>F</sub> =10A |                       |                  | 0.41 | 0.45 |       |
|                                          | I <sub>F</sub> =1A  | T <sub>A</sub> =85°C  |                  | 0.22 | 0.27 |       |
|                                          | I <sub>F</sub> =2A  |                       |                  | 0.25 | 0.3  |       |
|                                          | I <sub>F</sub> =10A |                       |                  | 0.36 | 0.42 |       |
|                                          | I <sub>F</sub> =1A  | T <sub>A</sub> =125°C |                  | 0.16 | 0.20 |       |
|                                          | I <sub>F</sub> =2A  |                       |                  | 0.20 | 0.24 |       |
|                                          | I <sub>F</sub> =10A |                       |                  | 0.32 | 0.36 |       |
| Instantaneous reverse current            | Rated VR            | T <sub>A</sub> =25°C  | I <sub>R</sub>   | 0.23 | 0.3  | mA    |
|                                          |                     | T <sub>A</sub> =85°C  |                  | 14.5 | 18   |       |
|                                          |                     | T <sub>A</sub> =100°C |                  | 35   | 39   |       |
| Typical junction capacitance             | 4.0 V, 1 MHz        |                       | C <sub>J</sub>   | 0.95 |      | nF    |
| Typical thermal resistance <sup>1)</sup> | junction to ambient |                       | R <sub>θJA</sub> | 80   |      | °C/W  |
|                                          | junction to case    |                       | R <sub>θJC</sub> | 35   |      |       |
|                                          | junction to mount   |                       | R <sub>θJM</sub> | 20   |      |       |

Note:1), The thermal resistance from junction to ambient, case or mount, mounted on P.C.B with 30×30mm copper pads, 2 OZ, FR4 PCB

2): Mounted on recommended copper pad area, free air.

## Ratings and Characteristics Curves

(TA = 25°C unless otherwise noted)

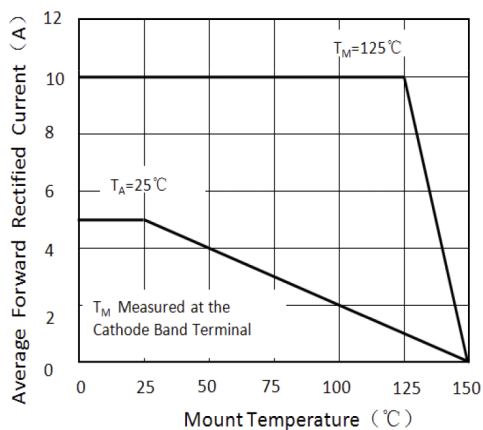


Figure 1. Forward Current Derating Curve

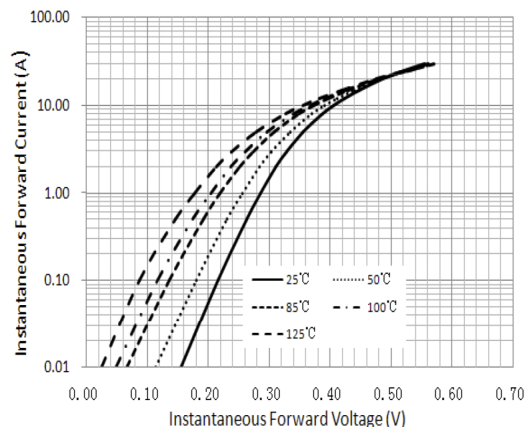


Figure 2. Typical Instantaneous Forward Characteristics

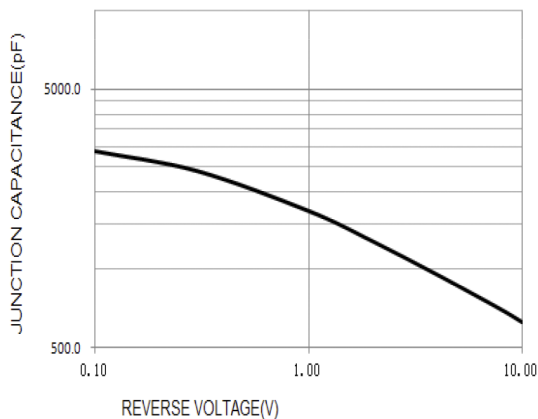


Figure 3. Typical Junction Capacitance

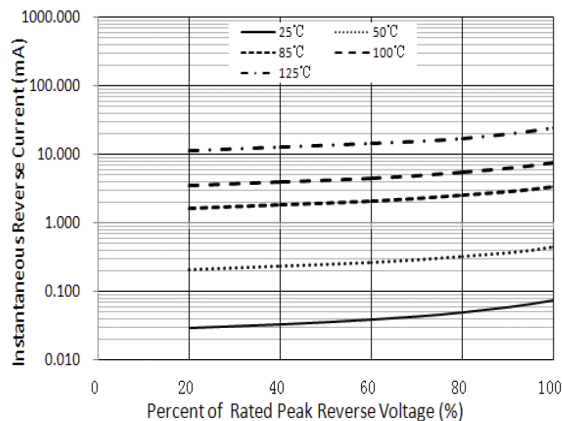


Figure 4. Typical Reverse Characteristics

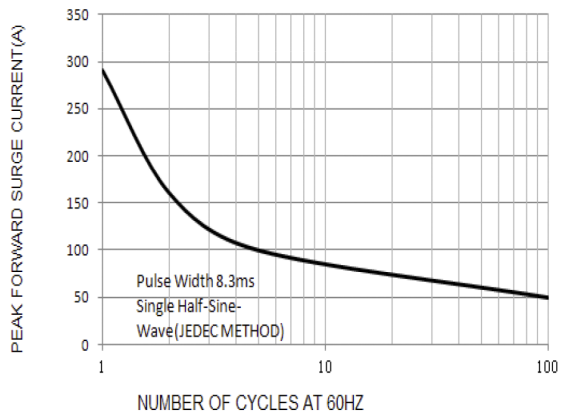
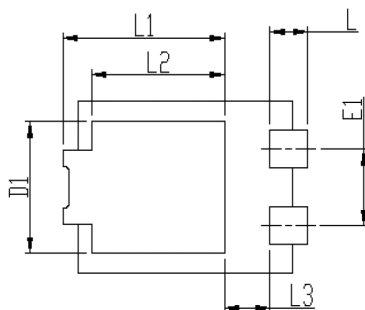
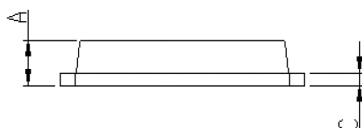
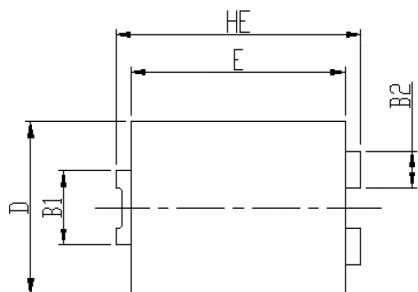


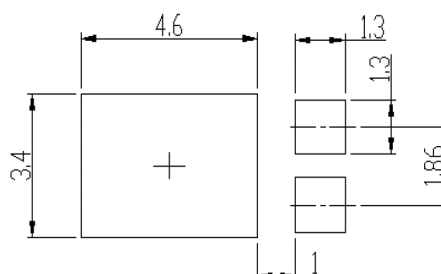
Figure 5. Maximum Non-Repetitive Peak Forward Surge Current

## Package Outline Dimensions



| DIM | Unit: mm  |     | Unit: inch |       |
|-----|-----------|-----|------------|-------|
|     | MIN       | MAX | MIN        | MAX   |
| HE  | 6.4       | 6.6 | 0.252      | 0.260 |
| E   | 5.6       | 5.8 | 0.220      | 0.228 |
| D   | 4.1       | 4.3 | 0.161      | 0.169 |
| B1  | 1.7       | 1.9 | 0.067      | 0.075 |
| B2  | 0.8       | 1   | 0.031      | 0.039 |
| A   | 1.05      | 1.2 | 0.041      | 0.047 |
| C   | 0.3       | 0.4 | 0.012      | 0.016 |
| L   | 0.85      | 1.1 | 0.033      | 0.043 |
| L1  | 4.2       | 4.4 | 0.165      | 0.173 |
| L2  | 3.52 Typ. |     | 0.139 Typ. |       |
| L3  | 1.1       | 1.4 | 0.043      | 0.055 |
| D1  | 3         | 3.3 | 0.118      | 0.130 |
| E1  | 1.86 Typ. |     | 0.073 Typ. |       |

Soldering footprint



## Packing Information

### Packing quantities:

5000 pcs/Reel, 12mm Tape, 13" Reel

### Tape & Reel Specification

